PCN	Num	ber:	202	20811	000	. 1				PCN Date:	August 11 2022	Ĺ,
Title	:	Qualification	of TI	Cheng	du a	as an	additional	Assembly si	te	for select dev	ices	
Cust	tome	r Contact:	PCN A	∧anage	r	Dep	t:	Quality Se	rvi	ces		
Proposed 1 st Ship Date: Nov				lov 16	16, 2022		Sample requests accepted until:			Sept 16, 202	2*	
*Saı	mple i	requests recei	ved af	ter (Se	ept	16 20	22) will not	t be support	ed			
Cha	nge 1	уре:										
\boxtimes		mbly Site	·			Des				Wafer Bum		
		mbly Process					Sheet			Wafer Bum	•	
\boxtimes		mbly Materials			<u>Ц</u>		number cl	hange	<u>Ц</u>	Wafer Bum	•	
		nanical Specific			<u> </u>		Site		<u> </u>	Wafer Fab		
	Pack	ing/Shipping/I	_abelir	ng	Ш	Test	Process		<u>닏</u>	Wafer Fab		
						-	N D - t - "		Ш	Wafer Fab	Process	
D						PC	N Detail	IS				
		on of Change										
		truments is ple elect Devices I					•			_		,
	Assembly Site		Ass	Assembly Site Origin			Assembly Country Code			Assembly City		
		UTAC		NSE			THA			Bangkok		
		TI Clark		QAE	3		PHL		1	Angeles City, Pampanga		
	T.	I Chengdu		CDA			CHN			Cheng	du	1
												_
Grou	up 1	Material Diffe	erenc	es:								
						UT	AC		ΤI	Chengdu		
		Die thickness		15			mils		10.5mils			
	ļ											
Grou	up 2	Material Diffe	erenc	es:								
	_					TI C	lark		ΤI	Chengdu		
		Die attach				4212				1223872		
	Mold compound		nd			4208				1222198		
Reason for Change:												
		of supply.			-		. O !!!	au Daliahil	·	(_
None		ed impact or	i Forn	1, FIT,	Fui	ictioi	i, Quality	or Kellabii	ity	(positive /	negative)	:
1m b	act o	n Environme	ntal F	katıng	S							
	Checked boxes indicate the status of environmental ratings following implementation of this change. If below boxes are checked, there are no changes to the associated environmental ratings.											

Changes to product identification resulting from this PCN:

REACH

RoHS

☑ No Change

Green Status

☑ No Change

IEC 62474

☑ No Change

Assembly Site		
UTAC	Assembly Site Origin (22L)	ASO: NSE
TI Clark	Assembly Site Origin (22L)	ASO: QAB
CDAT	Assembly Site Origin (22L)	ASO: CDA

Sample product shipping label (not actual product label)



LBL: 5A (L)T0:1750



(1P) SN74LS07NSR (Q) 2000 (D) 0336 (31T)LOT: 3959047MLA (4W) TKY(1T) 7523483S12 (P) (2P) REV: (V) 0033317 (20L) CSO:SHE (21L) CCO:USA (22L) ASO:MLA (23L) ACO:MYS

Group 1 Product Affected:

LMR36503RFRPER	LMR36506R5RPER	LMR36506RFRPER
LMR36506R3RPER	LMR36506RF3RPER	LMR36506RRPER

Group 2 Product Affected:

BQ29700DSER	BQ29707DSER	BQ29718DSER	BQ29729DSER
BQ29700DSET	BQ29707DSET	BQ29718DSET	BQ29729DSET
BQ29701DSER	BQ29717DSER	BQ29723DSER	
BQ29701DSET	BQ29717DSET	BQ29723DSET	

Group 1 Qualification Report

Approve Date 16-June-2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	Test Name	Condition	Duration	Qual Device: LMR36506xRxRPER	QBS Reference: <u>B</u> Q <u>25792R</u> Q <u>MR</u>	QBS Reference: LMR36506MSCQRPERQ1
HAST	Biased HAST	110C/85%RH	264 Hours	-	-	3/231/0
HAST	Biased HAST	130C/85%RH	96 Hours	-	3/231/0	-
UHAST	Autoclave	121C/15psig	96 Hours	-	-	3/231/0
UHAST	Unbiased HAST	130C/85%RH	96 Hours	-	3/231/0	-
TC	Temperature Cycle	-55C/125C	700 Cycles	-	3/231/0	-
TC	Temperature Cycle	-65C/150C	500 Cycles	1/77/0	-	3/231/0
HTSL	High Temperature Storage Life	150C	1000 Hours	-	-	3/135/0
HTSL	High Temperature Storage Life	170C	420 Hours	-	3/231/0	-
HTOL	Life Test	150C	408 Hours	-	-	3/231/0
ESD	ESD CDM	-	500 Volts	-	-	1/3/0
ESD	ESD HBM	-	2000 Volts	-	-	1/3/0

LU	Latch up	150C	100mA	-	-	1/3/0
SD	Solderability	4 hour 155C aging	Pb free	-	1/15/0	1/15/0

QBS: Qual By Similarity

Qual Device LMR36506xRxRPER family is qualified at MSL2 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours The following are equivalent Temp Cycle options per JESD47: -55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at Tl's external Web site: http://www.ti.com/

Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

Group 2 Qualification Report

Approve Date 03-August-2022

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Туре	#	Test Name	Conditio n	Duration	Qual Device: BQ29700DS ER	QBS Reference: BQ29700DSER	QBS Reference: <u>PTPIC2020RT</u> Q <u>RG4</u>	QBS Reference: <u>TPS3703C7500DS</u> <u>ER</u> Q <u>1</u>
HAST	A2	Biased HAST	130C/85 %RH	96 Hours	-	-	-	2/154/2 ¹
UHAST	A3	Unbiased HAST	130C/85 %RH	96 Hours	-	-	-	2/154/0
TC	A4	Temperature Cycle	- 65C/150 C	500 Cycles	-	1/77/0	-	2/154/0
HTSL	A6	High Temperature Storage Life	150C	1000 Hours	-	-	-	2/154/0
HTSL	A6	High Temperature Storage Life	170C	420 Hours	-	1/77/0	-	-
HTOL	B1	Life Test	125C	1000 Hours	-	-	3/231/0	-
ESD	E2	ESD CDM	-	250 Volts	-	1/3/0	-	-
ESD	E2	ESD HBM	-	1000 Volts	-	1/3/0	-	-
LU	E4	Latch-Up	Per JESD78	-	-	1/3/0	-	-
CHAR	E5	Electrical Characterizati on	Per Datashee t Paramet ers	-	-	1/Pass	-	-

QBS: Qual By Similarity

Qual Device BQ29700DSER is qualified at MSL2 260C

Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable

The following are equivalent HTOL options based on an activation energy of 0.7eV: 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours

The following are equivalent HTSL options based on an activation energy of 0.7eV: 150C/1k Hours, and 170C/420 Hours

The following are equivalent Temp Cycle options per JESD47:-55C/125C/700 Cycles and -65C/150C/500 Cycles Quality and Environmental data is available at Tl's external Web site: http://www.ti.com/ Green/Pb-free Status: Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail				
WW PCN Team	PCN www admin team@list.ti.com				

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